

描述 / Descriptions

双向触发二极管，薄型 SOD-123FL 封装。

Silicon Bidirectional Trigger Diodes, SOD-123FL thin package.

特征 / Features

适用于晶闸管相控，调灯电路，通用电机速度控制器，热量控制。无卤产品。

Use in thyristor phase control,circuits for lamp-dimming,universal-motor speed controls,and heat controls.Halogen free product.

用途 / Applications

一般用途.

General purpose.

内部等效电路 / Equivalent Circuit

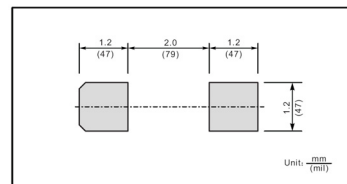


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Power Dissipation (T _C =100°C)	P _{tot}	150	mW
Repetitive Peak On-state Current (tp=20us, f=100Hz)	I _{TRM}	2	A
Operating Junction and Storage Temperature Range	T _j T _{stg}	-40 to +125	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	最大值 Max	单位 Unit	
Breakover Voltage	V _{BO}	C=22nF see diagram 1	DB3W	28	36	V
			DC34W	30	38	V
			DB4W	35	45	V
Breakover Voltage Symmetry	[+V _{BO} - -V _{BO}]	C=22nF see diagram 1	—	3	V	
Dynamic Breakover Voltage	ΔV±	ΔI=[I _{BO} to I _F =10mA]	5	—	V	
Output Voltage	V _O	See diagram 2	5	—	V	
Breakover Current	I _{BO}	C=22nF	—	50	uA	
Leakage Current	I _B	V _B =0.5 V _{BO} max	—	10	uA	
Rise Time	t _r	See diagram 3	—	2	us	

电参数曲线图 / Electrical Characteristic Curve

Diagram1: current-voltage characteristic

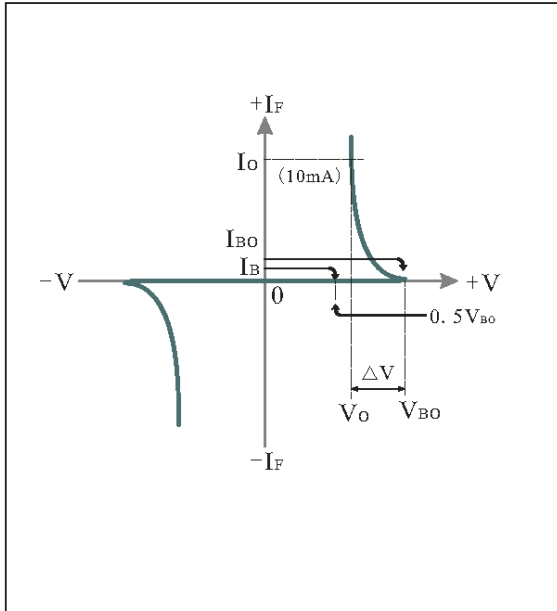


Fig.1: Power dissipation versus ambient temperature(maximum values)

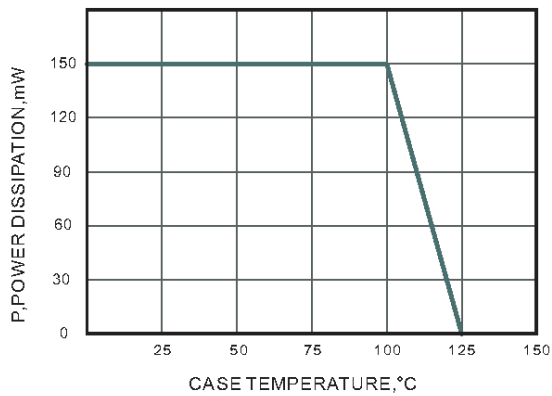


Fig.3: Power dissipation versus ambient temperature(maximum values)

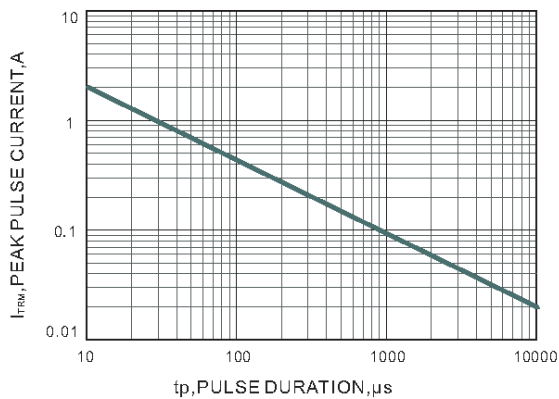


Diagram2: Test circuit for output voltage

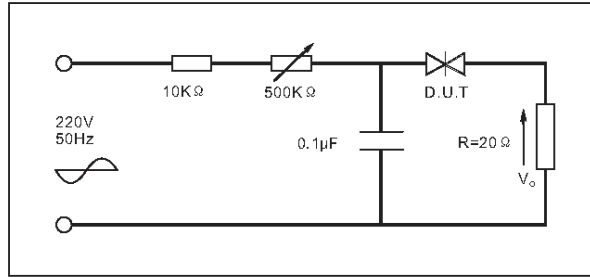


Diagram3: Test circuit see Fig.2. Adjust R for $I_p=0.5\text{A}$

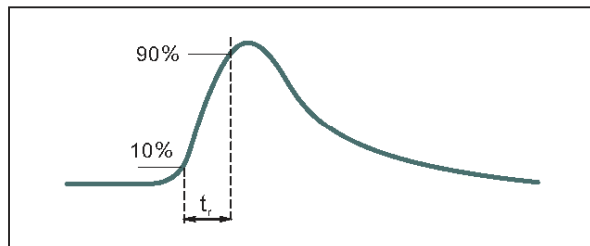
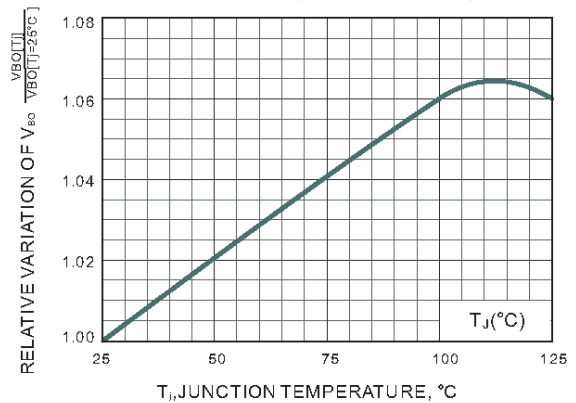
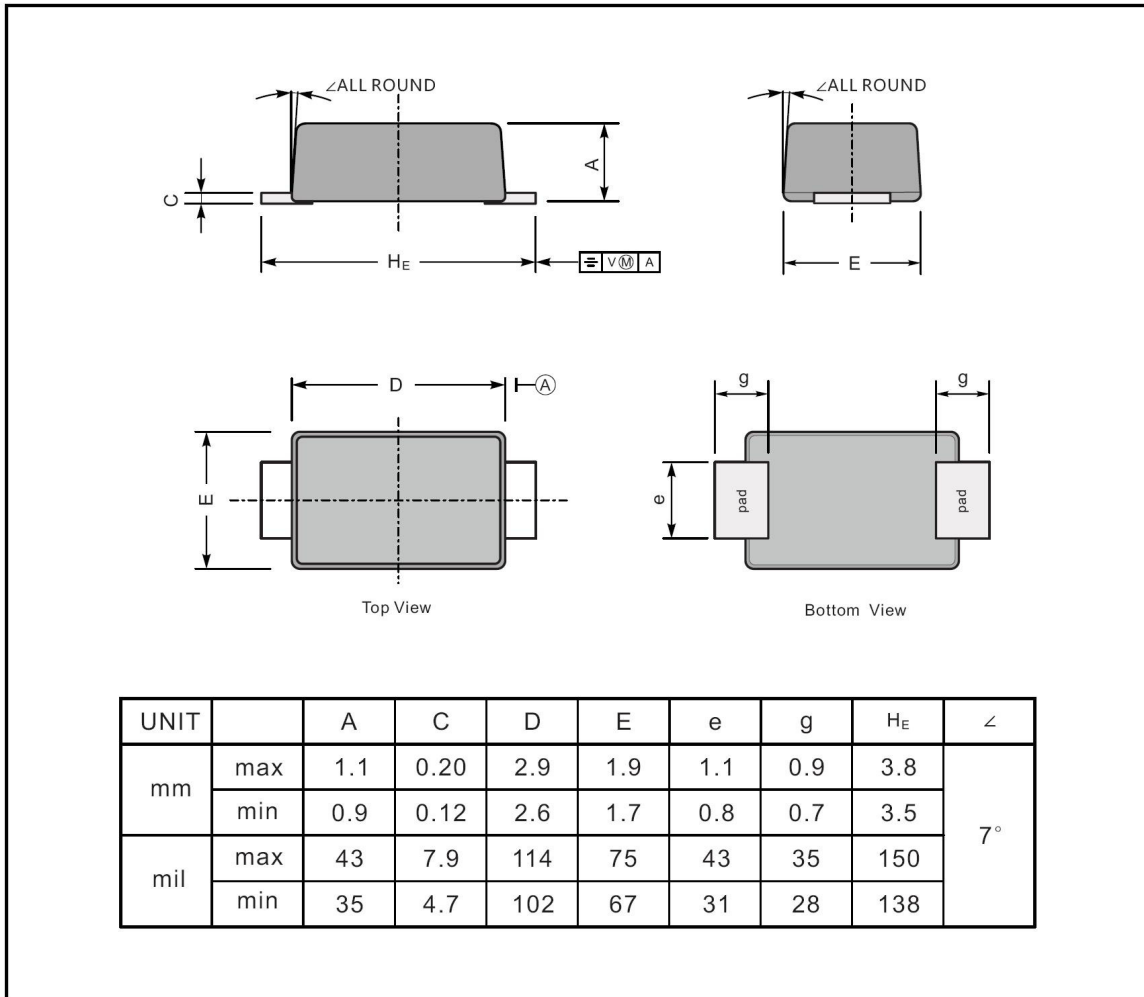


Fig.2: Power dissipation versus ambient temperature(maximum values)



外形尺寸图 / Package Dimensions

SOD-123FL



Marking

Type number	Marking code
DB3W	DB3W
DC34W	DC34W
DB4W	DB4W

印章说明 / Marking Instructions



说明：

DB3W：为型号代码

****：为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

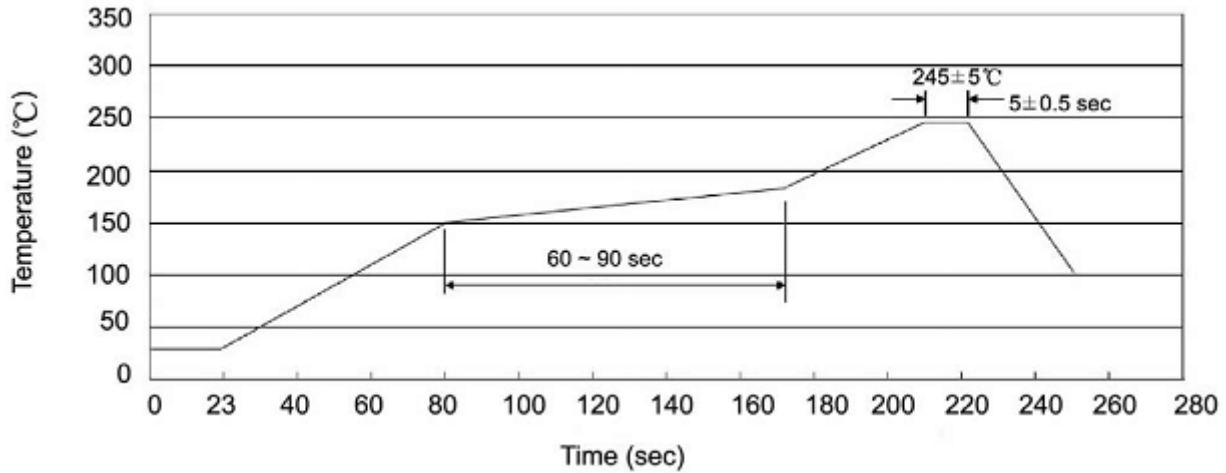
Note:

DB3W：Product Type Code

****：Lot No. Code，The 1st "*" means:YM Code，The last 3 "*" means:little Lot

No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123FL	3000	8	24000	5	120000	7" ×11	185X180X105	390X385X205

使用说明 / Notices